WHAT IS CLAIMED IS:

1. A method of forming an electrical connection between two devices, comprising:

bonding an interconnection on a first contact pad of a first component, wherein said interconnection comprises

a conductive polymer comprising a polymer component and a conductive component; and,

a first solderable cap disposed in contact with said conductive polymer; and,

soldering said first solderable cap to a second contact pad of a second component.

2. The method of claim 1, wherein said polymer component comprises a thermoplastic polymer, a copolymer, or a blend, and said conductive component comprises electrically conductive particles.

3. The method of claim 2, wherein said polymer component comprises a nylon, polysulfone, polyester, polyimide, siloxane, ethylene, vinyl acetate, aryl-ether, polyutethane, polyisocyanate, polyether, polyester, acrylate, or polyvinyl chloride.

4. The method of claim 2 wherein said conductive particles comprise gold, silver, palladium, oxide free noble alloys of gold, silver, and palladium, or a noble metal.

5. The method of claim 1, wherein said first solderable cap comprises gold, nickel, silver, copper, zinc, palladium, platinum, indium, tin, bismuth, or lead.

6. The method of claim 1, wherein said first solderable cap has a width and a thickness, and said width is about 0.010 inches to about 0.050 inches, and said thickness is about 0.002 inches to about 0.01 inches.

7 The method of claim 1, wherein said conductive polymer has a width and a thickness, and said width is about 0.010 inches to about 0.050 inches, and said thickness is about 0.002 inches to about 0.058 inches.

8. The method of claim 1, wherein said conductive polymer has a resistivity of less than about 0.05 ohms per centimeter.

9. The method of claim 1, wherein said first solderable cap is a solder ball.

10. The method of claim 1 wherein said bonding comprises placing said interconnection in contact with said first contact pad and heating said conductive polymer.

11. The method of claim 1 wherein said bonding comprises:

applying said conductive polymer in an uncured state on said first contact pad;

disposing said first solderable cap in contact with said conductive polymer; and,

curing said conductive polymer.

12. A method of forming an electrical connection between two devices, comprising:

soldering a second solderable cap of an interconnection to a first contact pad of a first component, wherein said interconnection comprises:

a conductive polymer comprising a polymer component and a conductive component;

a first solderable cap disposed in contact with said conductive polymer; and,

said second solderable cap disposed in contact with said conductive polymer opposite said first solderable cap; and,

soldering said first solderable cap to a second contact pad of a second component.

13. The method of claim 12, wherein said polymer component comprises a thermoplastic polymer, a copolymer, or a blend, and said conductive component comprises electrically conductive particles.

14. The method of claim 13, wherein said polymer component comprises:

a nylon, polysulfone, polyester, polyimide, siloxane, ethylene, vinyl acetate, aryl-ether, polyutethane, polyisocyanate, polyether, polyester, acrylate, or polyvinyl chloride.

15. The method of claim 13 wherein said conductive particles comprise gold, silver, palladium, oxide free noble alloys of gold, silver, and palladium, or a noble metal.

16. The method of claim 12, wherein said first solderable cap and said second solderable cap comprise gold, nickel, silver, copper, zinc, palladium, platinum, indium, tin, bismuth, or lead.

17. The method of claim 12, wherein said first solderable cap and said second solderable cap have a width and a thickness, and said width is about 0.010 inches to about 0.050 inches, and said thickness is about 0.002 inches to about 0.01 inches.

18. The method of claim 12, wherein said conductive polymer has a width and a thickness, and said width is about 0.010 inches to about 0.050 inches, and said thickness is about 0.002 inches to about 0.058 inches.

19. The method of claim 12, wherein said conductive polymer has a resistivity of less than about 0.05 ohms per centimeter.